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(12) United States Patent Bergman

(10) Patent No.:

US 6,497,768 B2

(45) Date of Patent:

*Dec. 24, 2002

(54) PROCESS FOR TREATING A WORKPIECE WITH HYDROFLUORIC ACID AND OZONE

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(73) Assignee: Semitool, Inc., Kalispell, MT (US)

(*) Notice: Subject to any disclaimer, the term of this

patent is extended or adjusted under 35

U.S.C. 154(b) by 0 days.

This patent is subject to a terminal disclaimer.

(21) Appl. No.: 09/929,312

(22) Filed: Aug. 14, 2001

(65) Prior Publication Data

US 2002/0050279 A1 May 2, 2002

Related U.S. Application Data

(63) Continuation of application No. 09/621,028, filed on Jul. 21, 2000, which is a continuation-in-part of application No. PCT/US99/08516, filed on Apr. 16, 1999, which is a continuation-in-part of application No. 09/061,318, filed on Apr. 16, 1998, now abandoned, which is a continuation-in-part of application No. 08/853,649, filed on May 9, 1997, now Pat. No. 6,240,933.

(51)	Int. Cl. ⁷	B08B 3/00 ; B08B 5/00;
		C23G 1/02
(52)	U.S. Cl	134/3; 134/2; 134/25.4;
` ´	134/30; 134/31	; 134/33; 134/41; 134/902
(58)	Field of Search	134/2, 3, 25.4.

134/30, 31, 33, 41, 102.1, 102.2, 108, 111, 199, 902

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(57) ABSTRACT

A workpiece or substrate is placed in a support in a reaction chamber. A heated process liquid is sprayed onto the substrate. The thickness of the layer of process liquid formed on the substrate is controlled, e.g., by spinning the substrate. Ozone is introduced into the reaction chamber by injection into the liquid or into the reaction chamber, while the temperature of the substrate is controlled, to chemically process the substrate. The substrate is then rinsed and dried.

28 Claims, 7 Drawing Sheets

